

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of	:	Confirmation No.: 7364
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TSUKASA MATSUDA et al.	:	Group Art Unit: 1762
	:	
Appln. No.: 10/673,910	:	Examiner: STOUFFER, Kelly M.
	:	
Filed: September 30, 2003	:	
	:	
FOR: METHOD FOR DEPOSITING METAL LAYERS USING SEQUENTIAL FLOW DEPOSITION	:	

December 26, 2007

AMENDMENT – AFTER NON-FINAL REJECTION

Mail Stop Amendment
United States Patent and Trademark Office
Customer Service Window
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

This paper is responsive to the Office Action mailed August 27, 2007. The present response includes the following:

Amendments to the Specification:	None
Amendments to the Claims:	Pages 2-9
Amendments to the Abstract:	None
Amendments to the Drawings:	None
Remarks:	Pages 10-13